

2. Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$

3. Thermal Resistance from Junction to Ambient, Lead Length = 1/2" on P.C. Board with

0.2" x 0.2" Copper Surface. 4. Pulse lest: tp = 300 uS, Duty Cycle < 2%.





This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.